

High Speed Infrared Emitting Diodes, 890 nm, Surface Emitter Technology

VSMY2890RGX01



VSMY2890GX01



DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2890 series are infrared, 890 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Automotive sensors
- Photointerrupters
- Emitter source for proximity sensors
- IR illumination

FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 890$ nm
- Angle of half intensity: $\phi = \pm 10^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2500X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr) at $I_F = 100$ mA	ϕ (°)	λ_p (nm)	t_r (ns)
VSMY2890RGX01	135	± 10	890	15
VSMY2890GX01	135	± 10	890	15

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2890RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2890GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity

**ABSOLUTE MAXIMUM RATINGS** ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5$, $t_p = 100\text{ }\mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	$^{\circ}\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	According to Fig. 9, J-STD-020	T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction-to-ambient	JESD51	R_{thJA}	250	K/W

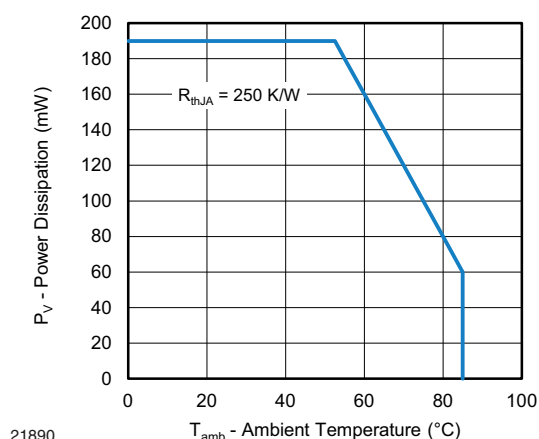


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

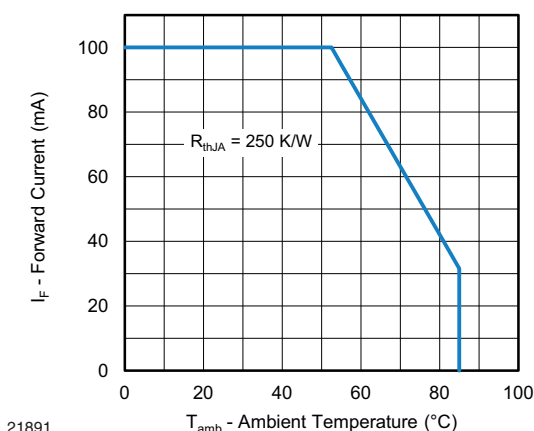


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	V_F	-	1.7	1.9	V
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	V_F	-	2.8	-	V
Temperature coefficient of V_F	$I_F = 100\text{ mA}$	TK_{VF}	-	-2.0	-	mV/K
Reverse current		I_R	Not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0\text{ mW/cm}^2$	C_J	-	60	-	pF
Radiant intensity	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	I_e	50	135	175	mW/sr
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	I_e	-	1000	-	mW/sr
Radiant power	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	ϕ_e	-	55	-	mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	TK_{ϕ_e}	-	-0.12	-	%/K
Angle of half intensity		φ	-	± 10	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	870	890	910	nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$	-	35	-	nm
Temperature coefficient of λ_p	$I_F = 100\text{ mA}$	TK_{λ_p}	-	0.3	-	nm/K
Rise time	$I_F = 100\text{ mA}$, 10 % to 90 %	t_r	-	15	-	ns
Fall time	$I_F = 100\text{ mA}$, 10 % to 90 %	t_f	-	15	-	ns



BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

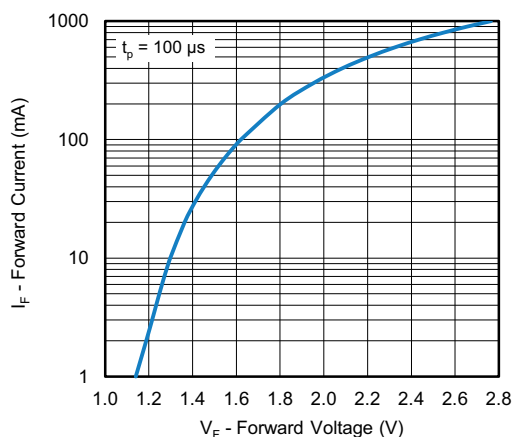


Fig. 3 - Forward Current vs. Forward Voltage

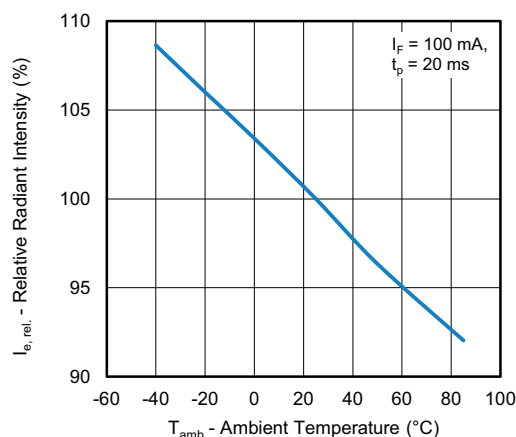


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

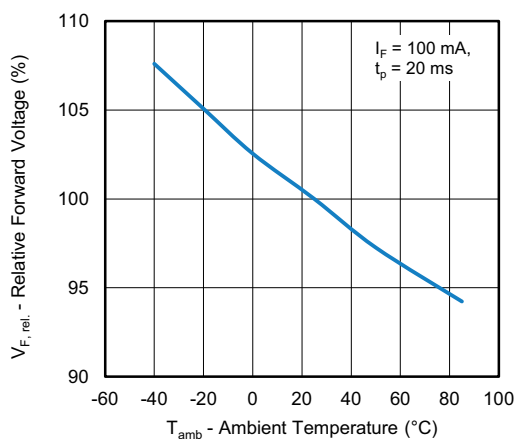


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

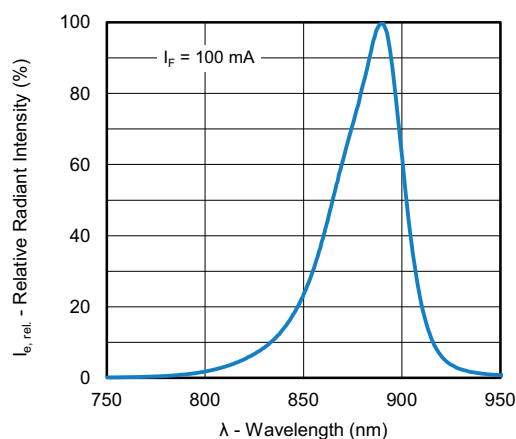


Fig. 7 - Relative Radiant Intensity vs. Wavelength

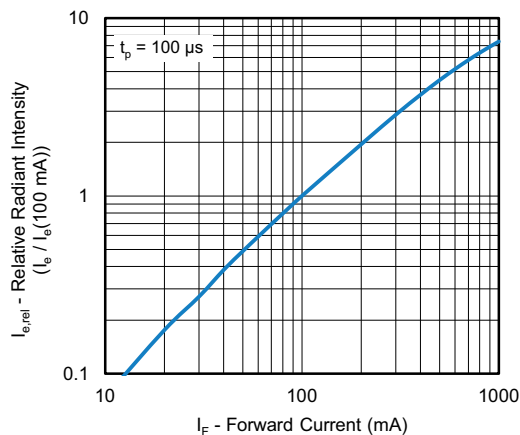


Fig. 5 - Relative Radiant Intensity vs. Forward Current

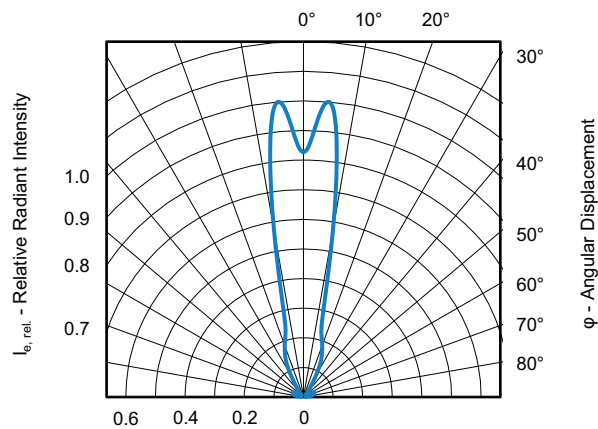


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



SOLDER PROFILE

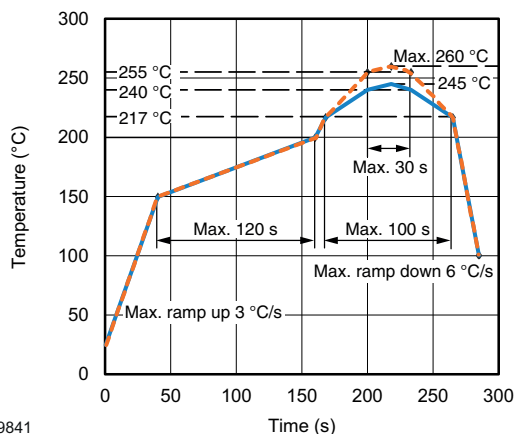


Fig. 9 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

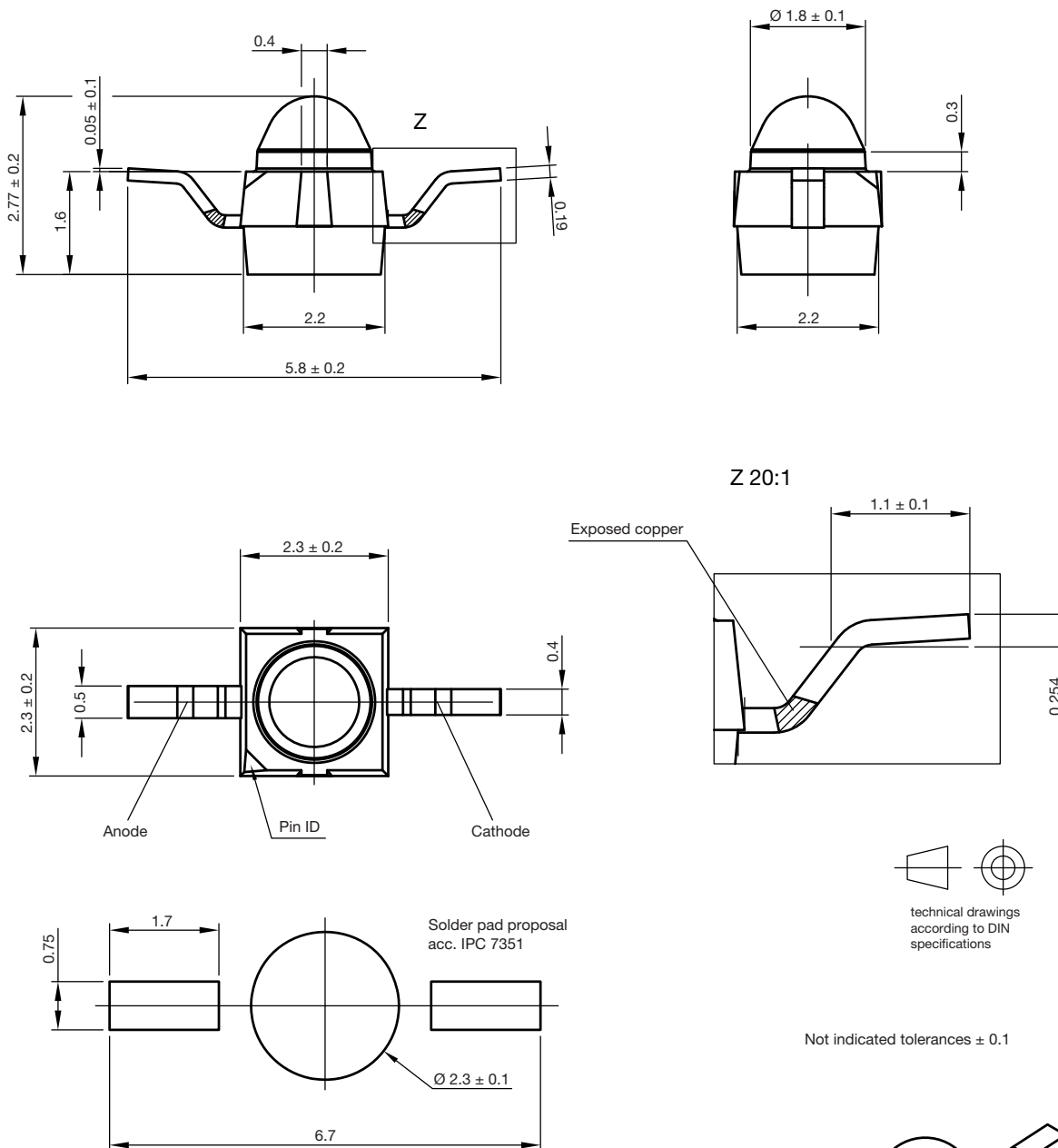
Moisture sensitivity level 2a, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.



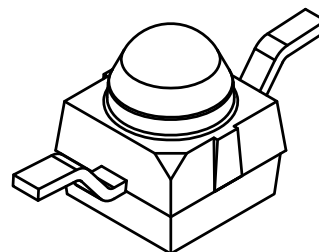
PACKAGE DIMENSIONS in millimeters: VSMY2890RGX01



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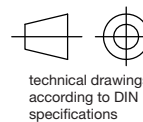
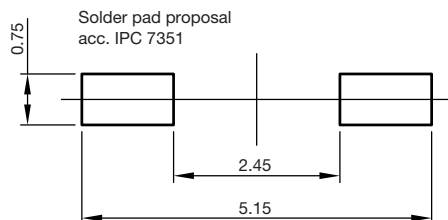
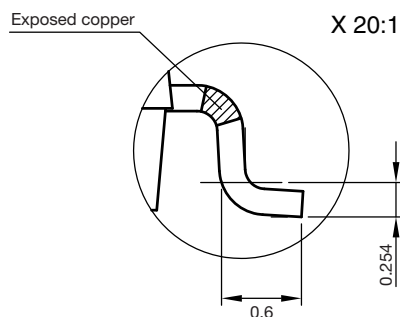
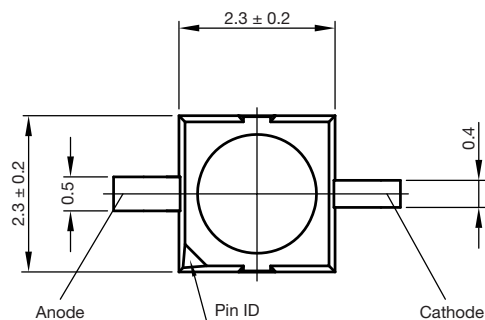
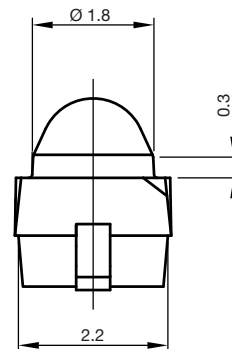
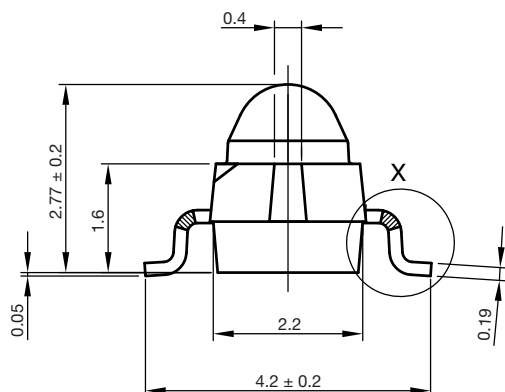
Issue: 1; 18.03.10

22100



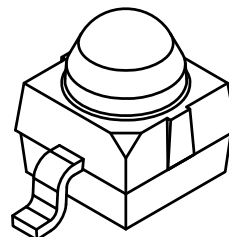


PACKAGE DIMENSIONS in millimeters: VSMY2890GX01

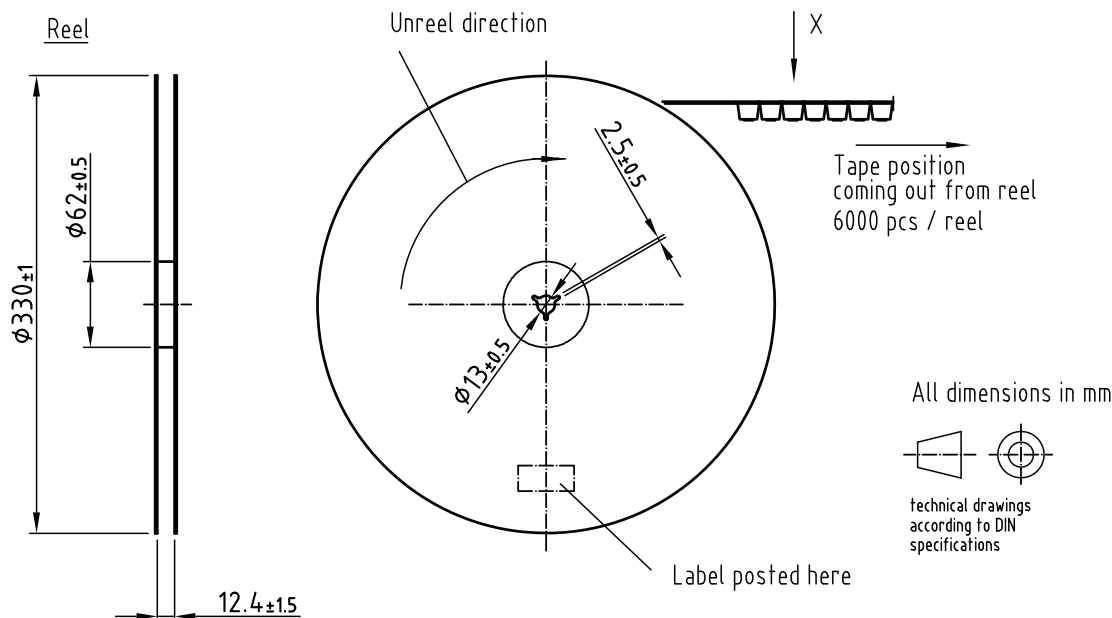
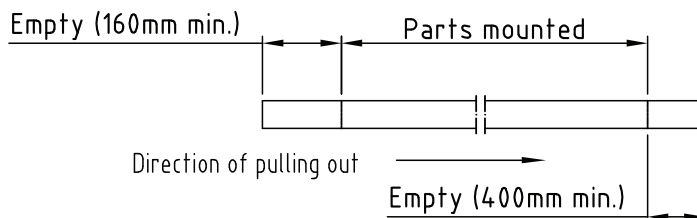


technical drawings
according to DIN
specifications

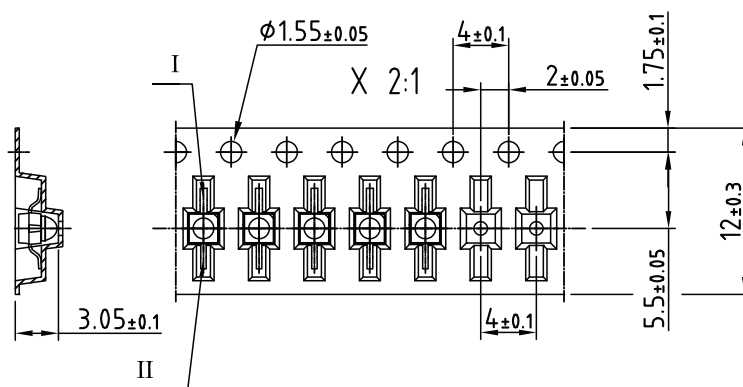
Not indicated tolerances ± 0.1



Drawing-No.: 6.544-5383.03-4
Issue: 1; 18.03.10
22099

TAPING AND REEL DIMENSIONS in millimeters: VSMY2890RGX01

Leader and trailer tape:

Terminal position in tape

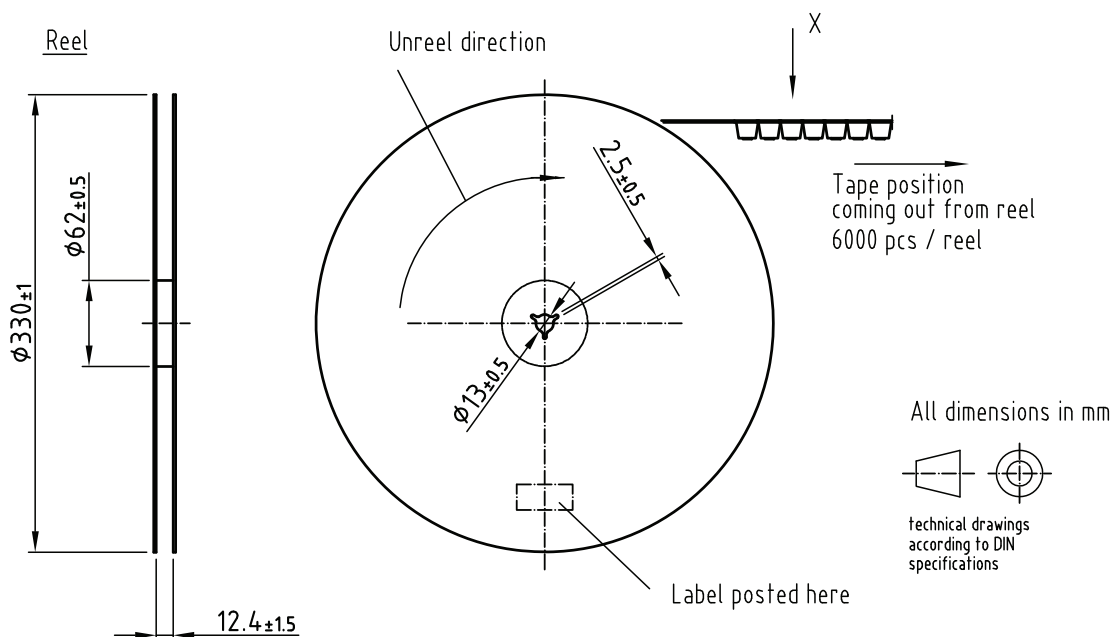
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VEMT 2000	Collector	Emitter
VEMT 2500		
VEMD 2000	Cathode	Anode
VEMD 2500		
VSMB 2000		
VSMG 2000		
VSMF 2890 RG	Anode	Cathode
VSMB 294008 RG		
VSMY 2xxx		
VSMF 288011 RG		



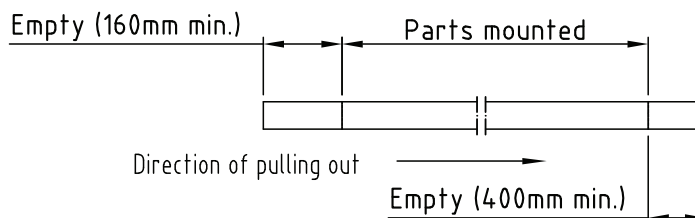
Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5100.01-4
Issue: preliminary, 11.07.19

TAPING AND REEL DIMENSIONS in millimeters: **VSMY2890GX01**

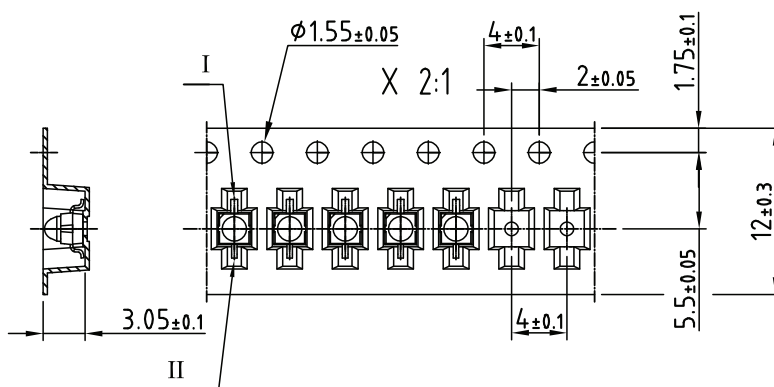


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VSMB 2020	Cathode	Anode
VSMG 2020		
VEMD 2020		
VEMD 2520		
VSMF 2890 G		
VSMB 294008 G		
VEMT 2020	Collector	Emitter
VEMT 2520		
VSMT 2xxx	Anode	Cathode
VSMF 288011 G		



Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5091.01-4
Issue: preliminary, 11.07.19



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